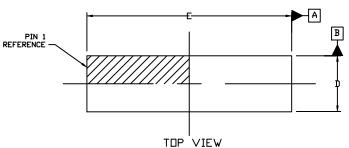
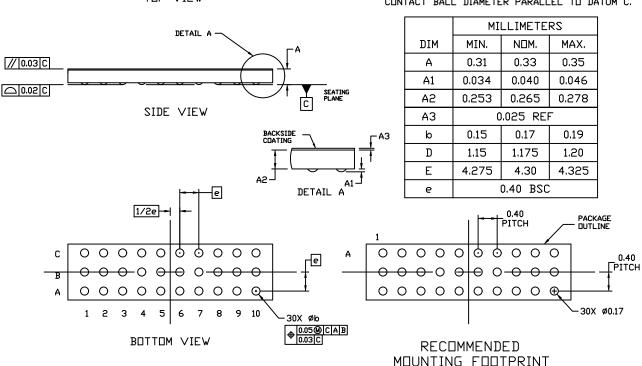
WLCSP30 1.175x4.3X0.33 CASE 567WE ISSUE O

DATE 28 MAR 2018



NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.



GENERIC MARKING DIAGRAM*

XXXXXXXX AWLYYWW XXXXX = Specific Device Code A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week *This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

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